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(54) Title: ENABLING MICRO-BUMP ARCHITECTURES WITHOUT THE USE OF SACRIFICIAL PADS FOR PROBING A WAFER

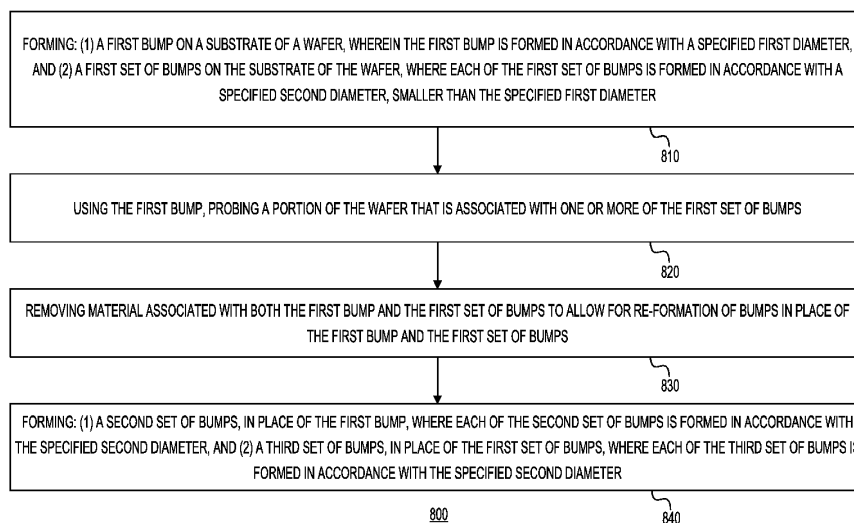


FIG. 8

(57) Abstract: Methods for enabling micro-bump architectures without the use of sacrificial pads for probing a wafer are described. A method includes forming: (1) a first bump in accordance with a specified first diameter, and (2) a first set of bumps in accordance with a specified second diameter, smaller than the specified first diameter. The first bump is used for probing a portion of the wafer associated with the first set of bumps. Both the first bump and the first set of bumps are then removed. The method includes forming: (1) a second set of bumps, in place of the first bump, where each of the second set of bumps is formed in accordance with the specified second diameter, and (2) a third set of bumps, in place of the first set of bumps, where each of the third set of bumps is formed in accordance with the specified second diameter.

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